# **NXP Semiconductors**

**Application Note** 

# **PT2000 Diagnostics**

## 1 Introduction

This application note explains how to use PT2000 diagnostics in a typical six cylinder internal combustion engine (ICE) application. The field of power train is just one example where diagnostics are required at very high speed. The PT2000 diagnostics manage this through six independent microcores.

This application note seeks to address different fault cases and describes how to program the microcode to detect them during idle and actuation mode.

NXP analog ICs are manufactured using the SMARTMOS process, a combinational BiCMOS manufacturing flow that integrates precision analog, power functions, and dense CMOS logic together on a single cost-effective die.

## 2 Overview

The PT2000 is a 15-channel gate driver IC for automotive engine control applications. The IC consists of seven external MOSFET high-side pre-drivers and eight external MOSFET low side pre-drivers. The PT2000 provides a flexible solution for the MOSFET's gate drive with a versatile control and optimized latency time. Gate drive, diagnosis, and protection are managed through six independent microcores, three Code RAM, and three Data RAM banks.

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APPLICATION SCHEMATIC

## 3 Application Schematic

The PT2000 typical application controls three injection banks, one DC-DC and a pump bank.



Figure 1. Typical Six Injector Three Bank Application Schematic

## 4 Application Instructions

This topology can be used on the evaluation board KITPT2000FRDM6C. Register settings and microcode downloads can be achieved by using the KL25Z embedded on the KITPT2000FRDM6C.

Each bank is individually managed by one microcore of the digital channel 1 as described next:

- The bank # 1 is managed by the digital microcore Uc0Ch1 with diagnostics
- The bank # 2 is managed by the digital microcore Uc1Ch1 with diagnostics, but no description is provided in this document since it is a simple copy paste from the previous bank. Microcode is available.
- The bank # 3 is managed by the digital microcore Uc0Ch2 with diagnostics, but no description is provided on this document since it is a simple copy paste from the previous bank. It is programmed on the microcode example available on the web.

The two microcores of the second channel (Channel 3) drive the DC-DC and the fuel pump as described next:

- The VFM (Variable Frequency Modulation) is managed by the digital microcore Uc1Ch3
- · The fuel pump is managed by the digital microcore Uc0Ch3

# This application note only focuses on BANK1 diagnostics managed by the digital microcore Uc0Ch1. Refer to AN5187 for register settings and microcode related to injection or DC-DC, unless specified in this document.

The following is the start-up sequence:

- Apply a battery voltage between 9.0 V and 16 V
- · Download the registers Channel Configuration, Main Configuration, IO Configuration, and Diagnostic Configuration
- Download the dedicated microcode in the Logic Channel 1, Logic Channel 2 and Logic Channel 3 Data RAM
- Set '1' in the pre-flash enable bit and en dual seq bit in the Flash\_enable register of channel 1 (100h), channel 2 (120h) and channel 3 (140h)

The register configurations and the microcodes are detailed in the following chapters.

Parameter Name	Description	Value
IBOOST	Current threshold in Boost Phase	14 A
I <sub>PEAK</sub>	Current threshold in Peak Phase (Depends on injectors type)	6 A
I <sub>HOLD</sub>	Current threshold in Hold Phase	3 A
<sup>t</sup> PEAK_OFF	Fixed time for high-side switch off in Peak Phase	10 μs
<sup>t</sup> PEAK_TOT	Fixed time for end of Peak Phase	500 μs
t <sub>bypass</sub>	Fixed time for Bypass Phase	20 µs
t <sub>HOLD_OFF</sub>	Fixed time for high-side switch off in Hold Phase	10 μs
t <sub>HOLD_TOT</sub>	Fixed time for end of Hold Phase (timeout)	10 ms
t <sub>INJMAXBOOST</sub>	Maximum time allowed to reach I <sub>BOOST</sub> (Depends on injectors type)	500 μs

## Table 1. Example of Injection Current Profile Key Parameters

#### **Diagnostics interrupts description:**

Diagnostics interrupts are handled in two different subroutines: automatic interrupt and software interrupt.

Status\_reg\_uc0 register (105h) is used to inform MCU on error detected, and then control register is used to unlock the Bank.

In all cases, the IRQB pin is set low to inform the MCU about the error detected in PT2000.

Interrupts can be filtered by their req id (stored in Uc0\_irq\_status Registers 10Fh):

Pre-Diagnostics checks (req id = 0): interrupt occurs if the high-side V<sub>BOOST</sub> / V<sub>BAT</sub>, V<sub>DS</sub> or V<sub>SRC</sub> are low or V<sub>DS</sub> low-side is low.

If an error occurs, the Status\_reg\_uc0 register (105h) bit 7 sets high, Bank1 sets OFF, and MCU needs to write a 1 to the control register (101h) bit 7 to unlock the Bank1.

Boost Error (Req id = 1): If  $I_{BOOST}$  is not reached before  $t_{INJMAXBOOST}$  = 500  $\mu$ s, this number has to be set according to the injector characteristics.

If an error occurs, Status\_reg\_uc0 register (105h) bit 5 sets high, Bank1 sets OFF, and MCU needs to write a 1 to the Ctrl\_reg\_uc0 register (101h) bit 5 to unlock the Bank1.

Hold Error (Req id = 2): If Start signal is still high after  $t_{HOLD OFF}$ .

If an error occurs, the Status\_reg\_uc0 register (105h) bit 4 sets high, Bank1 sets OFF, and MCU needs to write a 1 to the Ctrl\_reg\_uc0 register (101h) bit 4 to unlock the Bank1.

An automatic Interrupt occurs during actuation, if comparators feedback is different than the error table (see Diagnostics Configuration Registers).

If an error occurs, the Status\_reg\_uc0 register (105h) bit 6 sets high, Bank1 sets OFF, and MCU needs to write a 1 to the Ctrl\_reg\_uc0 register (101h) bit 6 to unlock the Bank1.

## Table 2. Status\_reg\_uc0 Registers (105h) Configuration

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name								statı	us_regis	ter						
Value	х	х	х	х	х	х	х	х	SW Interru pt Status	Auto Interru pt Status	Boost Error Status	Hold Error Status	х	x	Injector 2 Error Status	Injector 1 Error Status

Reading this register indicates the type of fault.

Table 3. Ctrl\_reg\_uc0 Registers (101h) Configuration

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name			con	trol_regi	ster_sh	ared						control_	registe	r		
Value	х	x	x	х	х	x	x	х	SW Interru pt Unlock	Auto Interru pt Unlock	Boost Error Unlock	Hold Error Unlock	х	x	х	х

Depending on the status register information, one of the bits must be set to 1 to unlock the BANK.

If an automatic diagnostics error is detected, it is possible to detect which failure occurred by reading the following registers to have an image when the failure occurred of the command, the  $V_{DS}$  and  $V_{SRC}$  state for each high-side and low-side. It allow detection of a short to ground, an open load, a short circuit to GND, or a short-circuit to  $V_{BAT}$ .

Table 4. Err	ucxchy	1 (1EDh	to 1FEh)
		- \	

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Reserv	cmd_H	Vsrc_H	Vds_H												
	ed	s5	s5	s5	s4	s4	s4	s3	s3	s3	s2	s2	s2	s1	s1	s1

## Table 5. Err\_ucxchy\_2 (1EDh to 1FEh)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	cksys_mis sing				ļ	Reserved	ł				cmd_H s7	Vsrc_H s7	Vds_H s7	cmd_H s6	Vsrc_H s6	Vds_H s6

## Table 6. Err\_ucxchy\_3 (1EDh to 1FEh)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	cmd_L	Vds_Ls														
	S8	8	S7	7	s6	6	s5	5	s4	4	s3	3	s2	2	s1	1

For example:

- IRQB pin pulled low
- MCU reads status register (105h) and detects Injector 1 fails during automatic diagnostics
- MCU then reads Err\_uc0\_ch1\_1 register (EDh) and detects that cmd\_HS1 = 1 and Vds\_Hs1 = 1, it means that a short to GND occurred on the HS1 (refer to <u>Table 13</u>)
- Depending on strategy, MCU decides to write control register (101h) to unlatch the fault and make another trial.

# 5 Diagnostic Descriptions

The PT2000 gives the possibility to check faults using two different methods:

- Automatic diagnostics (Actuation phase):
  - Boost Phase (HSBoost ON): automatic diagnostics are used during actuation phase; it performs a coherency check between an output and the related V<sub>DS</sub> feedback (for all the outputs) and V<sub>SRC</sub> feedback (for the high-side outputs only).
  - Peak and Hold phase (HSBat ON): automatic diagnostics are used during actuation phase; it performs a coherency check between an output and the related V<sub>DS</sub> feedback (for all the outputs) and V<sub>SRC</sub> feedback (for the high-side outputs only).
- Idle Diagnostics (Pre-actuation): Internal voltage biasing V<sub>BIAS</sub> should be applied to the load to enable diagnostics in this phase.



## Figure 2. Typical Peak and Hold Current Profile with Diagnostics

Several fault cases could occur in the application, this chapter describes most of them, and explains how the PT2000 is able to detect them.

## 5.1 Idle Diagnostics (Pre-actuation)

As described in Figure 2, idle diagnostics start after a rising edge on the start 1 or start 2 (Bank 1). A voltage biasing V<sub>BIAS</sub> should be applied to the load, to enable electrical diagnosis while the external load is not actuating the power stage.

This V<sub>BIAS</sub> voltage is generated by:

- the activation of the SRC<sub>PUX</sub> pull-up voltage source connected to each of the S\_HSx pins. Each pull-up voltage source is supplied from VCC5
- the activation of each SRC<sub>PDX</sub> pull-down current source connected to each of the D\_LSx pins. Each pull-down voltage source is referenced to ground

When the battery voltage  $V_{BATT}$  is in the nominal range or greater, the external load is biased at a minimum voltage of typically 3.8 V. In a low battery voltage condition ( $V_{BATT}$  < 8.0 V), the load is biased at half the  $V_{BATT}$  voltage, to guarantee symmetrical voltage margins to high-side and low-side VDS comparators.



Figure 3. Biasing Voltage vs. V<sub>BATT</sub>

The bias generators can be kept ON even during actuation, to control the voltage on the source, even if the MOSFET is OFF. This does not impact the application, because of their low strength. If at least one MOSFET is turned ON, it fixes the voltage on the load and does not affect the bias.

These pre-actuation diagnostics are used to ensure the injectors can be turned ON safely. If an error occurs in any of the following cases, the PT2000 keeps Bank 1 OFF until the MCU writes a 1 through the SPI to the Ctrl\_reg\_uc0 register (101h) bit 7.





Figure 4. Idle Normal Mode

#### DIAGNOSTIC DESCRIPTIONS

During normal operation, a current limited pull-up voltage source (SRC<sub>PUX</sub>) generates a voltage on S\_HSx (min. 3.8 V). Its current goes to the load and to a pull-down current source on D\_LSx, generating a 3.8 V min. voltage. Drain source voltage on the high-side is not monitored directly, and since there is no pin for the drain, monitoring is directly done from  $V_{BAT}$  or  $V_{BOOST}$ , and only HS2, HS4, and HS6 can use  $V_{BOOST}$  as a reference. Voltage thresholds are selected to be lower than the voltage generated.

## Table 7. Normal Mode Truth Table

Error Case	LSx_vds_fbk	HSx_src_fbk	Hsx_vds_Vbat_fbk	S_HSx voltage V <sub>BAT</sub>	D_LS_x voltage
Normal mode	1	1	1	3.8	3.8

## 5.1.2 High-side Source or Low-side Drain Shorted to GND





In cases where the High Source (S\_HSx) shorts to GND or the Low-side Drain (D\_LSx) shorts to GND, the current limited voltage source pulls to ground, and the voltage on S\_HSx and D\_LSx is 0 V. A diagnostic error is detected, and since the high-side  $V_{SRC}$  and low-side  $V_{DS}$  feedback are low, the bank does not turn ON.

Table 8. S\_HSx or D\_LSx Shorted to GND Truth Table

Error Case	LSx_vds_fbk	HSx_src_fbk	Hsx_vds_Vbat_fbk	S_HSx voltage V <sub>BAT</sub>	D_LS_x voltage
Normal mode	1	1	1	3.8	3.8
D_LS GND short	0	0	1	0	0

## 5.1.3 Drain Source Low-side Shorted to GND



Figure 6. Low-side Drain Source Shorted

In cases where the Low-side Drain Source shorts, D\_LSx pulls to 0 V, the current limited voltage source pulls to ground, and the voltage on S\_HSx and D\_LSx is 0 V. A diagnostic error is detected, since the high-side  $V_{SRC}$  and low-side  $V_{DS}$  feedback are low.

Table 9. Drain Source Low-side Shorted Truth Table

Error Case	LSx_vds_fbk	HSx_src_fbk	Hsx_vds_Vbat_fbk	S_HSx voltage V <sub>BAT</sub>	D_LS_x voltage
Normal mode	1	1	1	3.8	3.8
Low-side Drain Source Short	0	0	1	0	0

## 5.1.4 Drain Source High-side Shorted to VBAT



Figure 7. High-side Drain Source Shorted

The diagnostic fails in cases where the high-side drain source shorts. As a consequence, S\_HSx and D\_LSx pulls up to  $V_{BAT}$ , the difference between drain and source on the high-side goes negative, resulting in low feedback on the high-side  $V_{DS}$ .

Table 10. Drain Source High-side Shorted Truth Table

Error Case	LSx_vds_fbk	HSx_src_fbk	Hsx_vds_Vbat_fbk	S_HSx voltage V <sub>BAT</sub>	D_LS_x voltage
Normal mode	1	1	1	3.8	3.8
High-side Drain Source Short	1	1	0	14	14

## 5.1.5 Open Load



Figure 8. Open Load

If one of the sides of the load is not connected properly, there is no current path between S\_HSx and D\_LSx. The voltage on D\_LSx is forced to ground, because of the SRC<sub>PDX</sub> current pull-down. The diagnostic fails, because the low-side  $V_{DS}$  feedback is low.

### Table 11. OpenLoad Truth Table

Error Case	LSx_vds_fbk	HSx_src_fbk	Hsx_vds_Vbat_fbk	S_HSx voltage V <sub>BAT</sub>	D_LS_x voltage
Normal mode	1	1	1	3.8	3.8
OpenLoad on Low-side	0	1	1	3.8	0
OpenLoad on High-side	0	1	1	3.8	0

## 5.1.6 Faults Not Detected in Idle Phase

There are different cases that cannot be detected in the idle phase:

- High-side  $V_{BAT}$  or  $V_{BOOST}$  open: not possible to be detected since both are OFF in idle phase
- · LS open: not possible to be detected since it is OFF in idle phase
- · Short between load pins: not possible to detect, because it allows the bias current to pass through

All these faults are detected in the actuation mode only.

## 5.2 Actuation Phase

The bias voltage used for idle diagnostics is kept ON, to predict the voltage on each pin even if the MOSFETs are OFF. In this case, when the MOSFETs are OFF, there is a 3.8 V voltage on the high-side source. In each case, if an error occurs, the PT2000 turns bank 1 OFF, keeps it OFF, and sets the Status\_reg\_uc0 register (105h) bit 6 high until the MCU writes a 1 to the control register bit 6.

## 5.2.1 Actuation Diagnostics Peak and Hold phase (HS Boost OFF, HS Bat ON, LS ON)

## 5.2.1.1 Normal Mode



## Figure 9. Normal Mode Peak and Hold

During peak and hold phase, the low-side is fully ON and V<sub>BAT</sub> high-side is controlled in PWM to regulate the current inside the injector.

To have a device as flexible as possible, detection error during automatic diagnostics is configurable for each low-side and high-side. To configure which case leads the device to an error, it is necessary to set the registers "Error\_table" for each low-side  $V_{DS}$ , high-side  $V_{DS}$ , and high-side  $S_{RC}$  where diagnostics are needed (refer to Diagnostics Configuration Registers). In Normal mode, the PT2000 comparator outputs should be in the following state:

### Table 12. Actuation in Normal Mode Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	1	1

# 5.2.1.2 High-side (Bat or Boost) Source Shorted to GND



Figure 10. High-side Source Shorted to GND

When S\_HSx shorts to GND, the PT2000 detects an overcurrent, due to the  $V_{DS}$  monitoring on the  $V_{BAT}$  high-side. The high-side shuts down as soon as the current is substantial enough to generate a higher drop across the MOSFET than the threshold. In this case, it's important to set a threshold (1.0 V, in this case) and a filter time to the lowest value allowed by the application, to quickly detect it (refer to Filter time). The automatic diagnostic fails, because high-side  $V_{DS}$  feedback is high.

## Table 13. High-side Source Shorted to GND Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	1	1
S_HSx V <sub>BAT</sub> or V <sub>BOOST</sub> GND Short	0	0	1	1	0

This case is also applicable when there is a short between the two load pins, substantial current flows inside  $V_{BAT}$  HS and LS until the difference between drain and source is higher than the threshold.

# 5.2.1.3 High-side V<sub>BOOST</sub> Short Drain Source



Figure 11. High-side V<sub>BOOST</sub> Shorted

During a peak and hold phase,  $V_{BOOST}$  high-side should be OFF, but if there is a short-circuit between the drain and source, the voltage on the  $V_{BOOST}$  high-side source rises to  $V_{BOOST}$ . The automatic diagnostic fails, because  $V_{DS}$  on the  $V_{BOOST}$  high-side is low.

## Table 14. High-side $V_{\text{BOOST}}$ Drain Source Shorted Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	1	1
HSvboot Drain Source short	0	1	0	0	1

## 5.2.1.4 High-side V<sub>BAT</sub> Open



## Figure 12. High-side Open

During the peak and hold phase, high-side  $V_{BAT}$  is ON. If it's open or not controlled properly, S\_HSx voltage will be lower than expected. The automatic diagnostic fails because on  $V_{BAT}$  high-side, the  $V_{DS}$  feedback is high and  $V_{SRC}$  feedback is low.

## Table 15. High-side $V_{\text{BAT}}$ Open Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	1	1
HS vbat open	0	0	1	1	0

This case is only detectable in actuation mode.

## 5.2.1.5 Low-side Open



## Figure 13. Low-side Open

With the low-side open, current on the D\_LSx pin flows through the load to the internal pull-down (SCR<sub>PDX</sub>) and the voltage rises to  $V_{BAT}$ . Automatic diagnostics fail, because the low-side  $V_{DS}$  feedback is high.

## Table 16. Low-side Open Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	1	1
LS Open	1	1	0	1	1

This is one case only detectable in actuation mode.

# 5.2.1.6 Drain Low-side Shorted to V<sub>BAT</sub> or V<sub>BOOST</sub>



Figure 14. Drain Low-side Shorted

When the low-side drain is shorted to  $V_{BAT}$  or  $V_{BOOST}$  (low probability case), the voltage on D\_LSx rises to  $V_{BAT}/V_{BOOST}$ . Voltage thresholds and filter times must be set to the lowest value allowed by the application, to detect the error as fast as possible. The automatic diagnostic fails, because the low-side  $V_{DS}$  feedback is high.

## Table 17. D\_LS Battery Short Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	1	1
D_LS Batt short Depending on external MOS behavior	1	1	0	1	1

## 5.2.1.7 Cases Undetectable During Peak and Hold Phase

There are different cases that can't be detected during peak and hold phase:

- Drain low-side shorted to GND: not detectable since the low-side is ON, in this case (detectable in idle phase)
- High-side V<sub>BAT</sub> drain source shorted: not detectable since the high-side is ON, in this case (detectable in idle phase)
- High-side  $V_{BOOST}$  open: not detectable since the high-side  $V_{BOOST}$  is OFF in this mode (detectable during  $V_{BOOST}$  phase)

## 5.2.2 Actuation Diagnostics Boost Phase (HS Boost ON, HS Bat ON, LS ON)

During Boost phase, boost voltage is used to turn the injector ON as fast as possible, high-side  $V_{BOOST}$  and low-side are ON. The high-side  $V_{BAT}$  source needs to be turned ON, to avoid errors during diagnostics, which has no impact on the application. Another option would be to disable automatic diagnostics on the high-side  $V_{BAT}$  source during boost phase.

In this example, the PT2000 automatic diagnostics are configured using instruction "endiags" (refer to Application Source Code). During actuation phase, automatic diagnostics monitor HS  $V_{BAT} V_{DS}$ , HS  $V_{BAT} V_{SRC}$ , HS  $V_{BOOST} V_{DS}$ , and LS  $V_{DS}$  continuously. To simplify the diagnostics code, HS  $V_{BAT}$  is kept ON during Boost phase to avoid unwanted errors on the  $V_{BAT}$  source.

## 5.2.2.1 Normal Mode



#### Figure 15. Boost Phase Normal Mode

During boost phase, the high-side boost is fully ON to reach boost current as fast as possible, high-side  $V_{BAT}$  is ON (for diagnostic purposes), and the low-side is fully ON. As with the peak and hold phase, the high-side  $V_{BOOST}$  error table must be set-up accordingly (see Diagnostics Configuration Registers).

### Table 18. Boost Phase Normal Mode Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	0	1

## 5.2.2.2 High-side Boost Source Shorted to GND



Figure 16. High-side Source Shorted to GND

The same behavior as in the Peak and Hold phase except this time the short is from  $V_{BOOST}$  to GND. The comparator threshold must be set as low as possible to detect the overcurrent faster and avoid any damage to the MOS. The automatic diagnostic on high-side  $V_{BOOST}$  fails because  $V_{DS}$  monitoring is high.

## Table 19. High-side Boost Source Shorted to GND Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	0	1
HSvbat Drain Source short	0	0	1	1	0





## Figure 17. High-side V<sub>BOOST</sub> Open

When  $V_{BOOST}$  high-side is open, the voltage on S\_HSx floats and forced to 0 V, due to the parasitic leakage on the S\_HSx pin. The automatic diagnostic on high-side  $V_{BOOST}$  fails because  $V_{DS}$  feedback is high.

## Table 20. High-side Boost Open Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	0	1
HS vboot open	0	1	0	1	1

This case is undetectable in idle phase.

## 5.2.2.4 Low-side Open



## Figure 18. Low-side Open

When the low-side is not connected properly, the voltage on D\_LSx is around a  $V_{BOOST}$  of 65 V. The automatic diagnostic fails due to  $V_{DS}$  feedback on the low-side.

## Table 21. Low-side Open Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	0	1
LS open	1	1	0	0	1

This case is undetectable in idle phase.

# 5.2.2.5 Drain Low-side Shorted to V<sub>BAT</sub> or V<sub>BOOST</sub>



Figure 19. Drain Low-side Shorted to  $V_{BAT}$  or  $V_{BOOST}$ 

This is the same behavior as in the Peak and Hold phase, when the drain low-side is shorted to  $V_{BAT}$  or  $V_{BOOST}$  (Low probability), with a short to GND on  $V_{BOOST}$  or  $V_{BAT}$ . The automatic diagnostic fails, because the voltage on D\_LSx is higher than the  $V_{DS}$  threshold.

## Table 22. Drain Low-side Shorted to $V_{\text{BAT}}$ or $V_{\text{BOOST}}$ Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	0	1
D_LS Boost/Bat short	1	1	0	0	1

## 5.2.2.6 Cases Undetectable During Boost Mode

There are different cases undetectable in the Boost phase:

- Drain low-side shorted to GND: not detectable, since the low-side is ON in this case (detectable in the idle phase)
- High-side V<sub>BAT</sub> or V<sub>BOOST</sub> drain source shorted: not detectable, since in this case, high-side is ON (detectable in the idle phase)

## 6 Software

## 6.1 Interrupt State Machine

The following state diagrams describe how the MCU knows, which interrupt occurred, and which fault was detected during both automatic and software interrupts. For injectors actuation and DCDC state diagram, refer to AN5187.



Figure 20. Software Interrupt State Machine



Figure 21. Automatic Interrupt State Machine

## 6.2 General Registers Setup

Unless specified, use the register settings described in AN5187. Only registers related to diagnostics and interrupts are described in the following chapter.

## 6.2.1 Main Configuration Registers

## Table 23. Driver\_config Register (1A5h)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	F	Reserved	d	Overte mp_irq _en	Drv_en _irq_e n	Vboost _irq_e n	Vcc5_i rq_en	Vccp_i rq_en	Iret_en	Irq_uc 1_ch3 _en	lrq_uc 0_ch3 _en	Irq_uc 1_ch2 _en	lrq_uc 0_ch2 _en	lrq_uc 1_ch1 _en	lrq_uc 0_ch1 _en	lrq_uc _en
Value	Х	Х	Х	Х	Х	Х	1	Х	1	Х	Х	Х	Х	Х	Х	1

This register doesn't need to be set for the diagnostic on the external MOSFET, since it is handled in the microcode directly. If an error is detected, it forces IRQB low using the microcode. The return address (iret) is also determined in the microcode.

As an example, set vcc5\_irq\_en to '1', to force IRQB low in cases of undervoltage on VCC5. When the undervoltage is gone, the IRQB pin is kept low until the user writes a '1' in the uv\_vcc5 bit (Driver\_status register (1B2h)).

## 6.2.2 6.1.2 IO Configuration Registers

This register (one for each microcore) selects the feedback by which each microcore is enabled. Setting the bit to '1' generates an interrupt towards UcXChY, in case an error is detected on the HSx or LSx feedback.

## Table 24. Fbk\_sens\_uc0ch1 Register\_Part1 (154h)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Reserv ed	Hs7_V src_se ns	Hs6_V src_se ns	Hs5_V src_se ns	Hs4_V src_se ns	Hs3_V src_se ns	Hs2_V src_se ns	Hs1_V src_se ns	Reserv ed	Hs7_V ds_se ns	Hs6_V ds_se ns	Hs5_V ds_se ns	Hs4_V ds_se ns	Hs3_V ds_se ns	Hs2_V ds_se ns	Hs1_V ds_se ns
Value	0	0	0	0	0	0	1	1	0	0	0	0	0	0	1	1

## Table 25. Fbk\_sens\_uc0ch1 Register\_Part2(155h)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Name Reserved									Ls87_ Vds_s ens	Ls6_V ds_se ns	Ls5_V ds_se ns	Ls4_V ds_se ns	Ls3_V ds_se ns	Ls2_V ds_se ns	Ls1_V ds_se ns
Value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1

In this particular application (see the schematics in KITPT2000FRDM6C), microcore 0 Channel 1 controls HS1 as high-side  $V_{BAT}$  and HS2 as high-side  $V_{BOOST}$ , LS1 and LS2. As show in table Table 24, an interrupt is generated if an error occurs on LS2  $V_{DS}$ , LS1  $V_{DS}$ , HS2  $V_{DS}$ , HS1  $V_{DS}$ , HS2  $V_{SRC}$ , and HS1  $V_{SCR}$ .

## 6.2.2.1 Threshold settings

Each comparator threshold is set on three bits. The  $V_{DS}$  and  $V_{SRC}$  thresholds are defined by registers 16Bh and 16Ch, for the high-side pre-drivers, and by the Vds\_threshlod\_ls\_1 (16Fh) for the low-side pre-drivers.

As described during fault description, these threshold must be set according to the external MOSFET and maximum current level used in the application. As with KITPT2000FRDM6C,  $R_{DS(ON)}$  MOSFET ~40 m $\Omega$  (worst case condition). The maximum current used in this application is 14 A, and overcurrent detection (using V<sub>DS</sub> monitoring) must be set at around 40% higher than max. current allowed (20 A).

Threshold(2:0)	VSRC and VDS (V)
0000	0.00
1001	0.10
1010	0.20
1011	0.30
1100	0.40
0001	0.50
0010	1.0
0011	1.5
0100	2.0
0101	2.5
0110	3.0
0111	3.5

Table 26. V<sub>DS</sub> and V<sub>SRC</sub> Monitoring Typical Threshold Selection

#### High-side V<sub>DS</sub> Threshold Calculation

 $V_{DS}$  Threshold (HS) = Overcurrent x  $R_{DS(on)}$  = 20 A x 0.040  $\Omega$  = 0.8 V  $\rightarrow$  **1.0 V** threshold selected. In this case, overcurrent = 1.0 V/0.04  $\Omega$  = 25 A.

### Table 27. Vds\_threshold\_hs Register (16Bh)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	١	/ds_thr_	_Hs4			Vds_tł	nr_Hs3			Vds_tł	nr_Hs2			Vds_tł	nr_Hs1	
Value		0000	)			00	00			00	10			00	10	

### Low-side $V_{\text{DS}}$ Threshold Calculation

Low-side the V<sub>DS</sub> monitoring is done between D\_LSx and GND, sense resistance must be included in the calculation.

 $V_{DS}$  threshold (LS) = Overcurrent x ( $R_{DS(on)} + R_{SENSE}$ ) = 20 A x (0.040  $\Omega$  + 0.015  $\Omega$ ) = 1.1 V  $\rightarrow$  **1.0 V** threshold selected, in this case overcurrent = 1.0 V / 0.055  $\Omega$  = 18 A.

### Table 28. Vds\_threshold\_ls\_1 Register (16Fh)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name		Vds thr	Ls4			Vds t	hr Ls3			Vds t	hr Ls2			Vds t	hr Ls1	
Value		0000	)			00	000			00	)10			00	10	

## High-side SRC Threshold

 $V_{SRC}$  is used mostly during idle phases to understand the type of fault present. It is better to keep the "detection threshold" far from the polarization condition. During actuation in this application, recirculation is done through a diode, keeping the voltage of the HS source below ground. In this case, any  $V_{SRC}$  voltage is ok, to prevent false diagnostics. In order to avoid detecting noise and to be far from the 3.8 V threshold, the PT2000  $V_{SRC}$  threshold is set to 1.0 V

## Table 29. Vsrc\_threshold\_hs Register (18Bh)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	١	/src_thr	_Hs4			Vsrc_t	hr_Hs3			Vsrc_t	hr_Hs2			Vsrc_t	hr_Hs1	
Value		0000	)			00	000			00	10			00	10	

## 6.2.3 Channel 1 Configuration Registers

Unless specified, use the same settings specified in AN4849.

## Table 30. Ctrl\_reg\_uc0 Control Registers for the Microcore 0 (101h)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name			cont	trol_regi	ister_sh	ared						control	registe	r		
Value	х	х	х	х	х	х	х	х	SW Interru pt Unlock	Auto Interru pt Unlock	Boost Error Unlock	Hold Error Unlock	х	х	х	х

control\_register: Control bits 4,5,6,and 7 are used to control the turn ON of the bank after a fault occurs

- B4: if START pin is still high after t<sub>HOLD TOT</sub> is reached (see Application Source Code)
- B5: if I<sub>BOOST</sub> is not reached before the specified time
- · B6: if errors are detected during actuation (automatic diagnostics)
- · B7: if errors are detected during pre-actuation phase (idle diagnostics)

Entry point for each microcode and interrupt are specified by the following. It corresponds to the CRAM line where each microcore and interrupt start. With the new IDE software provided, this sets automatically using the **Settings Menu** by using the label as an address.

## Table 31. Uc0\_entry\_point Registers (10Ah)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name			Rese	erved	entry_point_address											
Value			000	000							10011	10000				

With the code provided, uc0 channel 1 starts line 2Ch label "init0", interrupt code should not be taken in account in the entry code.

## Table 32. Uc1\_entry\_point Registers (10Bh)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name			Rese	erved						e	ntry_poir	nt_addre	SS			
Value			000	000							00000	01000				

With the code provided, uc1 channel 1 starts line 74h label "init1".

The automatic and software interrupt is at the same address, label "irq\_detected" on the example provided. To differentiate them, the irq source register is used.

## Table 33. Diag\_routine\_addr Registers (10Ch, 12Ch)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name		Rese	erved			diagnosis_routine_address_uc1 diagnosis_routine_address_uc0										
Value		00	00				000	000					000	000		

• diagnosis\_routine\_address\_uc0: Automatic diagnostics are located at line 0 (label irq\_detected)

• diagnosis\_routine\_address\_uc1:Automatic diagnostics are located at line 0 (label irq\_detected)

The same settings on software interrupt are needed to specify the location in the CRAM where SW interrupts are handled.

## Table 34. Sw\_interrupt\_routine\_addr Registers (10Eh, 12Eh)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	sw_irq _falling _edge _start_ uc1	sw_irq _rising _edge _start_ uc1	sw_irq _falling _edge start_ uc0	sw_irq _rising _edge _start_ uc0	sof	ware_in	terrupt_r	outine_a	iddress_	uc1	sof	tware_in	terrupt_r	outine_a	ddress_	uc0
Value	х	х	х	х			000	000					000	000		

· software\_interrupt\_routine\_address\_uc0: Line 0 in the CRAM

• software\_interrupt\_routine\_address\_uc1: Line 0 in the CRAM

• sw\_irq\_rising\_edge\_start\_uc0: Not used in this example

• sw\_irq\_falling\_edge start\_uc0: Not used in this example.

## 6.3 Diagnostics Configuration Registers

### 6.3.1 LS1 and LS2 Output Register

### 6.3.1.1 Filter time

These registers define the automatic diagnostics filtering. Values depend on noise in the application and MOSFET switching time to get stable for reliable feedback when diagnostics start.

## Table 35. Lsx\_diag\_config1 Registers (1C0h, 1C3h)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Rese	erved	filter_t ype		filter_length				disable_window							
Reset	0	0	0		000101							0001110	)			

• filter type: Set to 0, in this case, means any different sample resets the filter counter

• filter\_length: The filtering time is:  $t_{FTN} = t_{CK} x (5.0 + 1.0) = 1/6$  MHz x 6.0 = 1.0  $\mu$ s

 disable\_window: this 7-bit parameter configures a time period during which any check on the LSx\_Vds\_feed signal is disabled after any change on the output\_command signal. t<sub>DTL</sub> = t<sub>CK</sub> x (14 + 4.0) = 1/6 MHz x 18 = 3.0 µs



### Figure 22. Filter Time and Disable Windows Diagram

#### 6.3.1.2 Error Table

Using the Diagnostic Descriptions section, error tables can be easily generated,

#### Table 36. Lsx\_diag\_config2 Registers (1C1h, 1C4h)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name		Reserved										error_table				
Reset	0000000000											10	01			

 error\_table: this 4-bit parameter defines the logical value of an error signal, issued from the output and the related V<sub>DS</sub> feedback signal. This table defines the output of the coherency check between the driven output and the acquired feedback; a logic one value means there is no coherency in the check, and then an error signal towards the microcore should be generated

## Table 37. Error Table for Both Low-sides

	output_command = 0 (Pre-driver switched OFF)	output_command = 1 (Pre-driver switched ON)
lsx_vds_fbk = 0 (V <sub>DS</sub> below threshold)	error_table (0) = 1	error_table (2) = 0 (OK)
lsx_vds_fbk = 1 (V <sub>DS</sub> above threshold)	error_table (1) = 0 (OK)	error_table (3) = 1

Normal mode in this application:

- Low-side is ON and the  $\mathsf{V}_{\mathsf{DS}}$  comparator should be low
- Low-side is OFF and the  $\mathsf{V}_{\mathsf{DS}}$  comparator should be high

## 6.3.2 HS1 / HS2 Output Register

## 6.3.2.1 Filter Time

Use the same filtering as the low-side, since the same MOSFET and slew rates are used for both.

## Table 38. Hsx\_diag\_config\_1 Registers (1D8h, 1DBh)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Rese	erved	Filter_t ype		filter_length				disable_window							
Reset	0	0	0		000101			0001110								

• filter\_type: Set to 0, in this case, means any different sample resets the filter counter

- filter\_length: The filtering time is:  $t_{FTN} = t_{CK} x (5.0 + 1.0) = 1/6 \text{ MHz} x 6.0 = 1.0 \ \mu s$
- disable\_window: this 7-bit parameter configures a time period during which any check on the LSx\_Vds\_feed signal is disabled after any change on the output\_command signal. t<sub>DTL</sub> = t<sub>CK</sub> x (14 + 4.0) = 1/6 MHz x 18 = 3.0 μs

## 6.3.2.2 Error Table

HS1 (VBAT) error table

## Table 39. Hsx\_diag\_config\_2 Registers (1D9h)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Reserved							error_table_src					error_table_vds			
Reset	0000000								01	10			10	01		

## Table 40. Error Table for High-side V<sub>DS</sub>

	output_command = 0 (Pre-driver switched OFF)	output_command = 1 (Pre-driver switched ON)
hsx_vds_fbk = 0 (V <sub>DS</sub> below threshold)	error_table_vds (0) = 1	error_table_vds (2) = 0
hsx_vds_fbk= 1 (V <sub>DS</sub> above threshold)	error_table_vds (1) = 0	error_table_vds (3) = 1

Normal mode in this application:

- High-side is ON and the V<sub>DS</sub> comparator should be low
- High-side is OFF and the V<sub>DS</sub> comparator should be high

## Table 41. Error Table for High-side V<sub>SRC</sub>

	output_command = 0 (Pre-driver switched OFF)	output_command = 1 (Pre-driver switched ON)
hsx_src_fbk = 0 (V <sub>SRC</sub> below threshold)	error_table_src (0) = 0	error_table_src (2) = 1
hsx_src_fbk = 1 (V <sub>SRC</sub> above threshold)	error_table_src (1) = 1	error_table_src (3) = 0

Normal mode in this application:

- High-side is ON and the  $V_{\mbox{\scriptsize SRC}}$  comparator should be high
- High-side is OFF and the V<sub>SRC</sub> comparator should be low

#### HS2 (VBOOST) error table

### Table 42. Hsx\_diag\_config\_2 Registers (1DCh)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Reserved							error_table_src error_table_vds								
Reset	0000000							0100				10	01			

	output_command = 0 (Pre-driver switched OFF)	output_command = 1 (Pre-driver switched ON)
hsx_vds_fbk = 0 (V <sub>DS</sub> below threshold)	error_table_vds (0) = 1	error_table_vds (2) = 0
hsx_vds_fbk= 1 (V <sub>DS</sub> above threshold)	error_table_vds (1) = 0	error_table_vds (3) = 1

	output_command = 0 (Pre-driver switched OFF)	output_command = 1 (Pre-driver switched ON)
hsx_src_fbk = 0 (V <sub>SRC</sub> below threshold)	error_table_src (0) = 0	error_table_src (2) = 1
hsx_src_fbk = 1 (V <sub>SRC</sub> above threshold)	error_table_src (1) = 0	error_table_src (3) = 0

 $V_{BOOST}$  high-side source detection is different in this application from  $V_{BAT}$  since S\_HSVbat and S\_HS\_VBoost are shorted together through a diode. If  $V_{BAT}$  high-side is ON, voltage on the  $V_{BOOST}$  source high-side is equal to  $V_{PWR}$  - diode. Consequently, the PT2000 should not detect an error on high-side  $V_{BOOST}$  if command = 0 and source feedback = 1.

## 7 Application Source Code

The following microcode can be directly downloaded from http://www.nxp.com/files/analog/doc/app\_note/AN5186SW.zip (see KITPT2000FRDM6C). Using the IDE and SPIGEN, the microcode can be downloaded to the PT2000.

#### 7.1 Injection Banks Management Source Code

\* This microcore will control BANK1 will check all diagnostics and detect the EOI using PT2000

#define HSBatB1 hs1; #define HSBoostB1 hs2; #define LS1B1 ls1; #define LS2B1 ls2; #define HSBatB2 hs3; #define HSBoostB2 hs4; #define LS1B2 ls3; #define LS2B2 ls4;

\*curl for ucore0 \*cur2 for uCore1

#include "dram1.def";

\* This flag is sent to the DCDC sequencer. It must be active for the whole period the boost voltage is used \* When the boost voltage is used, the DCDC must be deactivated \* flag = 0 => boost voltage is used, DCDC must be deactivated \* flag = 1 => boost voltage not used, DCDC can be active #define BstFlag b0; \* During the interrupt routine, the sequencer wait for this bit to be set to '1' before resuming execution of application code #define AutoDiagResetBit0 b6; During the interrupt routine, the sequencer wait for this bit to be set to '1' before resuming execution of application code #define IdleDiagResetBit0 b7; During the interrupt routine, the sequencer wait for this bit to be set to '1' before resuming execution of application code #define BoostResetBit0 b5; During the interrupt routine, the sequencer wait for this bit to be set to '1' before resuming execution of application code #define HoldResetBit0 b8;

stirq low;

\* Set flag0 high to release the DC-DC converter idle mode stf high BstFlag; \*################################# Check which injector was interrupted check inj: joidr check inj1 seq1; \* Check which ucore (sequencer) detected the error \* the last active injector was number 1 check inj0: joslr MarkInj1 start1; joslr MarkInj2 start2; \* the last active injector was number 2 \* jump to restore jmpr check irq; check inj1: joslr MarkInj3 start3; \* the last active injector was number 3 joslr MarkInj4 start4; \* the last active injector was number 4 jmpr check\_irq; \* jump to restore stsrb high Inj1FaultBit; \* mark the injector 1 as fault MarkInj1: jmpr check irq; stsrb high Inj2FaultBit; MarkInj2: \* mark the injector 2 as fault jmpr check\_irq; stsrb high Inj3FaultBit; MarkInj3: \* mark the injector 3 as fault jmpr check\_irq; stsrb high Inj4FaultBit; MarkInj4: \* mark the injector 4 as fault jmpr check irq; check irq: \* This register contains also the sw irq ID \*########## Check if its auto or sw interrupt \*\*\*\*\* ldirh 10h rst; \* load MSB in ir reg: 0x1000 in immediate register, to use as mask for irq status and IRQ\_stat Reg0;  $\star$  extract the irq source from irq status register (bits 12) jarr auto\_waitEnable0 all0; \* if the irq source is 0 => Automatic Diagnostics detected \* Else => a software interrupt occured go to next line ldirh ÖCh rst; as mask for irq status and IRQ stat Reg0; \* extract the sw id from irq status register (bits 11-10) and IRQ\_stat\_Reg0; \* extract the sw id from irq status register (bits 11-10) jarr Boost\_waitENO allO; \* if the sw id is 0 => Iboost never reached => go to Boost\_waitEN \* Else => error detected in idle diag=> go to next line => seq stuck until micro write 1 in control register b8 ldirh 08h rst; \* load MSB in ir reg: 0x0800 in immediate register, to use as mask for irq status and IRQ stat Reg0; \* extract the sw id from irq status register (bits 11-10) and IKQ\_stat\_KegU; \* extract the sw id from irq status register (bits 11-10)
jarr Idle waitEnable0 all0; \* if the sw id is 0 => Means IRQ = b01 => Idle diagnostics fails \* Else => Hold error => go to next line => idle diag fail Hold waitEN0: stsrb high HoldErrorBit0; \* Start pin stays higher longer than 10ms jcrr Hold waitENO HoldResetBit0 low; \* Wait here until control bit register b4 is write to 1 jmpr restore0; Idle waitEnable0: stsrb high IdleIrqBit0; \* IDle diag fail we set status b7 high to let user know which error occured jcrr Idle waitEnable0 IdleDiagResetBit0 low;\* Wait here until control bit register b7 is write to 1 jmpr restore0; auto waitEnable0: stsrb high AutoIrqBit0; \* Set status register bit 6 when automatic diagnosis interrupt trig jcrr auto waitEnable0 AutoDiagResetBit0 low; \* the sequencer is stuck here until the bit of the control register is set to '1' b6 \* Jump to restore jmpr restore0; Boost\_waitEN0: stsrb high BoostErrorBit0;
register bit b5 \* Iboost never reached, let user know by setting status jcrr Boost waitEN0 BoostResetBit0 low; \* Wait here until control bit register b5 is write to 1 restore0: stirq high; \* Set high IRQB pin \* Reset a) control registers rstreg all; b) status regsiter c) err seq register (status of automatic diagnosis d) re-enables irq generation from automatic diagnosis iret restart rst; \* Clear interrupt queue and restart from init phase INTT PHASE

\* Set low the IRQB pin

```
* ### Initialization phase ###
init0:
                                         \, * Set the gain of the opamp of the current measure block 1 \,
        stgn gain8.68 sssc;
                                    * Load the eoinj line label Code RAM address into the register jr1
        ldjr1 eoinj0;
        ldjr2 idle0;
                                      * Load the idle line label Code RAM address into the register jr2
         stirq high;
         cwef jr1 _start row1;
                                        * If the start signal goes low, go to eoinj phase
IDLE PHASE
                                        *****
* ### Idle phase- the uPC loops here until start signal is present ###
* Perform an actuation on inj1 if start 1 (only) is active
                                         * Perform an actuation on inj1 if start 2 (only) is active
                                            * Enable Offset Compensation
offcompONO: stoc on sssc;
         jmpr idle0;
                                         * jump back to idle0
SHORTCUT DEFINITION
* ### Shortcuts definition per the injector to be actuated ###
dfcsct dac1;
                                           * use current feedback1
                                        * Set the base address to 0 for Injector 1
         stab 0;
         jmpr idle_diag0;
                                           * Jump to launch phase
 ### Shortcuts definition per the injector to be actuated ###
* use current feedback1
         dfcsct dac1;
                                        * Set the base address to 10 for Injector 2
         stab 10;
         jmpr idle_diag0;
                                            * Jump to launch phase
PRE-ACTUATION DIAG PHASE
*****
                               *****
* All Vds should be high due to bias
* All HSs Vsrc should be high as well
                                           * Disable Offset Compensation
idle diag0:
            stoc off sssc;
                                       * Enable all biasing structures, kept ON even during actuation
         * Error detected if Vds of shortcut1 (HS) is low
         * Error detected if Vds of shortcut2 (LS) is low
           bias all on;
            jocr idle_diag_fail0 _sclv;
jocr idle_diag_fail0 _sc2v;
jocr idle_diag_fail0 _sc3v;
jocr idle_diag_fail0 _sc1s;
jocr idle_diag_fail0 _sc3s;
mor boostT0;
                                        * Error detected if Vds of shortcut3 (Boost) is low
* Error detected if Vsrc of shortcut1 (HS) is low
* Error detected if Vsrc of shortcut3 (Boost) is low
           jmpr boostT0;
                                        * Jump to actuation phase if no failure detected in idle phase
idle diag fail0:reqi 1;
                                          * Go to software subroutine is fault detected in idle phase
HSBat error
*****
                                     BOOST PHASE
*****
                                              -
- -
* ### Launch phase enable boost ###
boostT0: load Iboost dac_sssc_ofs;
ldcd rst_ofs keep keep injMaxTBoost c3;
ldcd rst_ofs keep keep injMinTBoost c2;
stf low BstFlag;
                                            * Load the boost phase current threshold in the current DAC
                                                * Start Boost Counter in case Iboost never reached
                                             * Start Boost Counter in case Iboost is reached too fast
                                               * Set flagO high to stop the DC-DC converter
* Turn VBAT off, BOOST on, LS on
         stos on on on;
                                               * Enable auto diag
         endiags on on on on;
                                               * After injMinBoost go to Boost T2
         cwer boostT1 tc2 row5;
                                               * Jump to error in case current is reached before the
         cwer boost_err0 ocur row2;
end of injMinBoost
         wait row125;
boostT1:
         cwer peak0 ocur row2;
                                               * Jump to peak phase when current is over threshold
                                            * Define Wait Table if actuation longer than injMaxGuard
        cwer boost_err0 tc3 row5;
go to eoinj
         wait row125;
boost err0: stf high BstFlag;
                                               * set flag0 high to release DCDC regulation
        regi 0;
                                             * Go to software subroutine is fault detected in Boost
phase, did not reach Iboost on time
PEAK PHASE
* ### Peak phase continue on Vbat ###
peak0: store cnt3 OpenInj record ofs; * Store opening time in the data in DRAM with offset to separate
```

#### APPLICATION SOURCE CODE

```
inj1 and 2
            stf high BstFlag;
ldcd rst _ofs keep Keep Tpeak_tot cl;
load Ipeak dac_sssc _ofs;
* set flag0 high to release the DC-DC converter idle mode
* Load the length of the total peak phase in counter 1
* Load the peak current threshold in the current DAC
            load Ipeak dac_sssc _ofs;
            cwer bypass0 tc1 row2;
                                                      \,^{\star} Jump to bypass phase when tcl reaches end of count
            cwer peak_on0 tc2 row3;
cwer peak_off0 ocur row4;
                                                     * Jump to peak on when tc2 reaches end of count
* Jump to peak_off when current is over threshold
peak_off0: ldcd rst _ofs keep keep Tpeak_off c2; * Load in the counter 2 the length of the peak_off phase
stos off on off; * Turn VBAT off, BOOST off, LS on
            wait row123;
                                                      * Turn VBAT on, BOOST off, LS on
peak on0: stos on on off;
            wait row124;
                                                      * Wait for one of the previously defined conditions
BYPASS PHASE
*****
* ### Bypass phase ###
bypass0: ldcd rst _ofs keep keep Tbypass c3;
stos off off off;
cwer hold0 tc3 row4;
* Load in the counter 3 the length of the off_phase phase
* Turn VBAT off, BOOST off, LS off
* Jump to hold when tc3 reaches end of count
                                                      * Wait for one of the previously defined conditions
            wait row14;
HOLD PHASE
*****
                                                     * ### Hold phase on Vbat ###
           phase on vbal ###
ldcd rst_ofs keep keep Thold_tot c1;
load Ihold dac_sssc_ofs;
cwer hold_error0 tc1 row2;
cwer hold_on0 tc2 row3;
cwer hold_off0 ocur row4;

* Load the length of the total hold phase in counter 2
* Load the hold current threshold in the DAC
* Jump to eoinj phase when tc1 reaches end of count
* Jump to hold_on when tc2 reaches end of count
* Jump to hold_off when current is over threshold
hold0:
hold_off0: ldcd rst _ofs keep keep Thold_off c2;  * Load the length of the hold_off phase in counter 2
    stos off on off;  * Turn VBAT off, BOOST off, LS on
                                                      * Turn VBAT off, BOOST off, L\overline{S} on
            wait row123;
                                                      * Turn VBAT on, BOOST off, LS on
hold on0: stos on on off;
            wait row124;
                                                      * Wait for one of the previously defined conditions
hold error0: regi 2;
                                                      * If Start high is longer than Thold tot go to sw interrupt
END OF INJECTION PHASE
                                                             _____
* ### End of injection phase ###
                                                     * Turn VBAT off, BOOST off, LS off
* Disable auto diag
           stos off off off;
eoinj0:
            endiaga diagoff;
                                                     * Enable all biasing structures, kept ON even during actuation
* set flag0 to high to release the DC-DC converter idle mode
* Go back to idle mode
           bias all off;
stf high BstFlag;
            jmpf jr2;
* ### End of Channel 1 - uCore0 code ###
*******

* Set the gain of the opamp of the current measure block 1
* Load the eoinj line label Code RAM address into the register jr1
* Load the idle line label Code RAM address into the register jr2
* If the start signal goes low, go to coing phase

* ### Initialization phase ###
          stgn gain8.68 sssc;
ldjr1 eoinj1;
ldjr2 idle1;
init1: stgn gain8.68 sssc;
            cwef jr1 _start row1;
                                                     * If the start signal goes low, go to eoinj phase
IDLE PHASE
* ### Idle phase- the uPC loops here until start signal is present ###
```

SHORTCUT DEFINITION \*\*\*\* dfcsct dac2; \* use current feedback1 \* Set the base address to 0 for Injector 1 stab 20; \* Jump to launch phase jmpr idle diag1; \* ### Shortcuts definition per the injector to be actuated ### dfcsct dac2; \* use current feedback1 \* Set the base address to 10 for Injector 2 stab 30: jmpr idle diag1; \* Jump to launch phase PRE-ACTUATION DIAG PHASE \* All Vds should be high due to bias \* All HSs Vsrc should be high as well stoc off sssc; \* Disable Offset Compensation idle diag1: stoc OIL SSSC, ias all on; jocr idle\_diag\_faill\_sclv; jocr idle\_diag\_faill\_sc2v; jocr idle\_diag\_faill\_sc3v; jocr idle\_diag\_faill\_sc1s; jocr idle\_diag\_faill\_sc3s; \* Enable all blacting for the form of the bias all on; jmpr boost1T0; idle diag fail1:reqi 1; \* Go to software subroutine is fault detected in idle phase HSBat error \*\*\*\* BOOST PHASE \*\*\*\* \* ### Launch phase enable boost ### boost1T0: load Iboost dac sssc ofs; \* Load the boost phase current threshold in the current DAC ldcd rst ofs keep keep injMaxTBoost c3; \* Start Boost Counter in case Iboost never reached \* Start Boost Counter in case Iboost is reached too fast ldcd rst ofs keep keep injMinTBoost c2; stf low BstFlag; \* Set flag0 high to stop the DC-DC converter \* Turn VBAT off, BOOST on, LS on stos on on on; \* Enable auto diag endiags on on on on; cwer boost1T1 tc2 row5; \* After injMinBoost go to Boost T2 \* Jump to error in case current is reached before the cwer boost\_err1 ocur row2; end of injMinBoost wait row125; \* Jump to peak phase when current is over threshold boost1T1: cwer peak1 ocur row2; \* Jump to peak phase when current is over energy \* Define Wait Table if actuation longer than injMaxGuard cwer boost\_err1 tc3 row5; go to eoinj wait row125; boost\_err1: stf high BstFlag; \* set flag0 high to release DCDC regulation \* Go to software subroutine is fault detected in Boost reqi 0; phase, did not reach Iboost on time PEAK PHASE \*\*\*\* \* ### Peak phase continue on Vbat ### peak1: store cnt3 OpenInj\_record ofs; \* Store opening time in the data in DRAM with offset to separate inj1 and 2 ldcd rst \_ofs keep keep Tpeak\_tot cl; \* Load the length of the total peak phase in counter 1
load Ipeak dac\_sssc \_ofs; \* Load the peak current threshold in the current DAC load Ipeak dac\_sssc \_ofs; cwer peak\_on1 tc1 row2; cwer peak\_on1 tc2 row3; cwer peak\_off1 ocur row4; \* Jump to bypass phase when tcl reaches end of count \* Jump to peak\_on when tc2 reaches end of count \* Jump to peak\_off when current is over threshold stf high BstFlag; \* set flag0 high to release the DC-DC converter idle mode peak\_off1: ldcd rst \_ofs keep keep Tpeak\_off c2; \* Load in the counter 2 the length of the peak\_off phase stos off on off; \* Turn VBAT off, BOOST off, LS on wait row123;

#### APPLICATION SOURCE CODE

peak_on1:	<pre>stos on on off; wait row124;</pre>	* Turn VBAT on, BOOST off, LS on * Wait for one of the previously defined conditions
* * * * * * * * * * * * *	**************************************	**************************************
********	***************************************	***************************************
* ### Bunae	s phase ###	
bypass1:	<pre>ldcd rst _ofs keep keep Tbypass c3; stos off off off; cwer hold1 tc3 row4; wait row14:</pre>	<pre>* Load in the counter 3 the length of the off_phase phase * Turn VBAT off, BOOST off, LS off * Jump to hold when tc3 reaches end of count * Wait for one of the previously defined conditions</pre>
	walt lowit,	wate for one of the previously defined conditions
* * * * * * * * * * * * * * *	**************************************	.*************************************
* * * * * * * * * * *	***************************************	***************************************
* ### Hold hold1:	<pre>phase on Vbat ###    ldcd rst _ofs keep keep Thold_tot c1;    load Ihold dac_sssc _ofs;    cwer hold_error1 tc1 row2;    cwer hold_on1 tc2 row3;    cwer hold_off1 ocur row4;</pre>	* Load the length of the total hold phase in counter 2 * Load the hold current threshold in the DAC * Jump to eoinj phase when tcl reaches end of count * Jump to hold on when tc2 reaches end of count * Jump to hold_off when current is over threshold
hold_off1:	<pre>ldcd rst _ofs keep keep Thold_off c2; stos off on off; wait row123;</pre>	* Load the length of the hold off phase in counter 2 $\star$ Turn VBAT off, BOOST off, $\rm L\overline{S}$ on
hold_on1:	<pre>stos on on off; wait row124;</pre>	* Turn VBAT on, BOOST off, LS on * Wait for one of the previously defined conditions
hold_error1	: reqi 2;	* If Start high is longer than Thold_tot go to sw interrupt
* * * * * * * * * * * * * * * * * * *	**************************************	**************************************
* ### End c	f injection phase ###	
eoinj1:	<pre>stos off off off; endiaga diagoff; bias all off; stf high BstFlag; jmpf jr2;</pre>	<pre>* Turn VBAT off, BOOST off, LS off * Disable auto diag * Enable all biasing structures, kept ON even during actuation * set flag0 to high to release the DC-DC converter idle mode * Go back to idle mode</pre>

\* ### End of Channel 1 - uCorel code ###

# 8 References

Following are URLs where you can obtain information on NXP products and application solutions:

Document Numbe	r and Description	URL			
PT2000	Data Sheet	www.nxp.com/files/analog/doc/data_sheet/MC33PT2000.pdf			
KITPT2000FRDM6C	User Guide	www.nxp.com/files/analog/doc/user_guide/KTPT2000FRDM6CUG.pdf			
PT2000SWUG	Programming Guide	www.nxp.com/files/analog/doc/user_guide/PT2000SWUG.pdf			
PT2000IDEUG	Developer Studio	www.nxp.com/files/analog/doc/user_guide/PT2000-IDEUG.pdf			
NXP.com Suj	oport Pages	URL			
NXP.com		www.nxp.com			
PT2000 Product Summary F	Page	www.nxp.com/PT2000			
Analog Home Page		www.nxp.com/analog			

# 9 Revision History

Revision	Date	Description
1.0	9/2015	Initial release
2.0	2/2016	<ul> <li>Reduced duration of Auto Diagnostics wave in Figure 2</li> <li>Updated Filter Time values in Section 6.3.1.1, Filter time, page 27</li> <li>Updated Filter Time values in Section 6.3.2.1, Filter Time, page 29</li> </ul>



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